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PATENT

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Date July 25 2002

Stephanie Jansen
Stephanie Jansen

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Tongbi Jiang

Attorney Docket No.: 500182.01 (660073.774)

Serial No. : 09/365,356

Group Art Unit : 2813

Filed : July 30, 1999

Examiner : Nema O. Berezny

Title : METHOD AND STRUCTURE FOR MANUFACTURING IMPROVED YIELD
SEMICONDUCTOR PACKAGED DEVICES

Box Non-Fee Amendment
Commissioner of Patents
Washington, DC 20231

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AMENDMENT

Sir:

Applicant acknowledges receipt of the Office Action dated April 29, 2002.

In the Claims:

Please cancel claims 5, 6, 7, 17 and 39, amend claims 1, 11, 38, 42, and add new claims 50-53 as follows:

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1. (Three Times Amended) A semiconductor device package, comprising:
a semiconductor die having a first surface on which an integrated circuit and at least one electrically conductive bond pad are fabricated, the die having first and second pairs of opposed lateral edges;
at least one electrically conductive external terminal;